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Subject: SSM JDP Project mtg: Minutes 2018-W03

SSM JDP PROJECT MEETING: 2018-WW03 MINUTES

SR71B data on lot 0170032.003 "BL tapering" (Mattia)

- Lot testing comments
 - Testing has moved to 85C
 - Low confidence of actual BL profile due to misprocess (wrong BL W thickness)
- Vt medians and Vt shift
 - As previously observed, 20nm WL W thickness has the downside of less effective seasoning (especially on low state). So the Vt evolution from 1k to 128k cycles is larger
 - Set seasoning seems partially better on no lamina groups
 - Tapered vs straight profile has ~100mV higher reset Vt with same set Vt
- Median drift 1us-10s @85C (128k cycles)
 - For no lamina groups drift is slightly higher
 - For the other 20nm W WL groups, drift is slightly lower than POR
 - Straight vs tapered profile @BL has higher drift
- Vt window and sigma
 - No lamina groups (aggressive tapering @WL) show the usual boost in median window. Higher In% results in more boost (tapering)
 - Tapered profile @BL has similar window with POR. Straight profile has lower window
 - 1k cycles sigma data is affected by poor seasoning
 - Reset sigma is higher than set, as usual when we have tapering with negative reading
 - Tapered BL profile has worse sigma
- Projected Vt window @ 3.54sigma

- In general, lower WL W thickness needs more cycling to get a decent window
- Exceptions are the no lamina groups, that perform well even after 1k cycles
- Conclusions and recommendations
 - Lower WL W thickness is confirmed to have an ineffective seasoning, especially for set distributions, and this is mitigated in no lamina stacks. Upside is a small reduction for drift
 - Tapered profile @BL groups have distributions with worse sigma and presence of high Vt tails. Small toggle of tapered vs straight BL profile, with an increase of window ~100mV. The increase is due to higher reset Vt
 - No lamina groups (aggressive tapering @WL) confirm window boost (neg read), with In 4% having a larger window
 - PFA needed to check actual morphology of trials

AR (Mattia): extend drift characterization to 2days@85C to completely assess the role of thin W

AR (Kolya): address physical analysis to verify the BL profiles for this lot

S26A probe data on lot 0173982.013 “K* camp on A1” (Lidia)

- Periphery yield
 - Decent and matched to trendline for 1D0 FS S26
- Structure health
 - Decent and matched to 1D0 FS S26 baseline
 - WLWL 2E/3E have more wfs with EOW OEDWL can be under chop and w2w, eventually send for PFA
 - BLBL outer ring shading not SWR related, CMPs?
 - OPENS mostly driven by WLICS, 1E has higher quarter WL fail possibly broken WL
- Memory effect
 - Gain is proportional with In%
 - + 200mV from 1E to 3E possibly underestimated
- Set sigma and drift
 - Set Sigma is 20mV lower for exp alloys
 - drift slope at 54-57 mV/dec almost matched among exp
 - VL for this lot is higher than prev K*
- SET fail
 - downside for exp grp, Near Cells Set Fails

SSM silicon update (Kolya)

- PROD SWRs
 - K* second wave 3 lots (based on Rev3.3)
 - 2 A0 7-way skews and 1 A1 4-way skew are all active in-line;
 - A1 lot shipped to Vimercate for testing
 - Additional SWRs in-line
 - A1 lot with reduced ambient is out
 - A1 lot with WSiN elimination skew
 - A1 with alloy #6 and WL single-step etch (Rev5 cell backup lot is also planned to start as soon as PVD chamber is ready)
 - A0 lot Camp N (with SiN-SAG)
 - Next development plan:
 - G* is more distant, Q2 activity
 - Dual deck setup is also Q2 activity, depending on the tape out schedule and first conversion layer
- Short term line conversions
 - Rev4.x – WSiN elimination; 55nm 2nd cut W
 - Rev5.x/6.x L1D and potential conversion in Q1'18
 - 65 NCMP FSL slurry and 350A 52 Nitride Cap
- Q1'18 priorities
 - Enable K* runner up alloy single step WL etch (Vt window demo)
 - NO Lamina (Cell rev5) – Mid February to probe
 - WITH lamina (Cell rev6) – Mid March to probe
 - Establish SSM Rev4.0 yield baseline (4-5 lots control groups on A1 material) as a basis for yield gap pareto to S26A full stack
 - **Initial yield summary can be based on control groups of lots SSM 30,34,36,37 lots by ww10**
- Dual-deck plan
 - Based on the reviewed tape-out plan, initial assessment on dual deck can be enabled by mid-Q2 (Si to probe)
 - Pull in and streamlining (reducing dependency on A3 and FPP) can potentially allow 2 full info-turns to probe on 2D before the end of Q2'18
 - Cell revision for 2D info-turns has to be defined before March (Rev6 D0 data still will not be available)